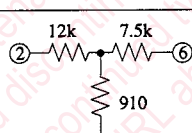


■ Absolute Maximum Ratings (Ta=25°C)

Item		Symbol	Rating		Unit
Voltage	Supply Voltage	V _{CC}	27.6		V
	Circuit Voltage	V ₂₋₁	0	60	V
		V ₄₋₁	0	60	V
		V ₆₋₁	0	2.5	V
		V ₇₋₁	0	1.3	V
Current	Supply Current	I _{CC}	250		mA
	Circuit Current	I ₂	-1000	1000	mA _{O-P}
		I ₈	-1000	1000	mA _{O-P}
Power Dissipation		P _D	6.66		W
Operating Ambient Temperature		T _{opr}	-20 ~ +70		°C
Storage Temperature		T _{stg}	-55 ~ +150		°C

⊕ refer to current flowing into IC, where as ⊖ refers to current flowing out of it.

■ Electrical Characteristics (Ta=25°C)

Item	Symbol	Test Circuit	Condition	min.	typ.	max.	Unit		
Deflection Current (Peak Value)	I _{Y(PP)}	1		860	930	1000	mApp		
Deflection Current Linearity	ΔI _{Y(+)}	1		25		75	mApp		
	ΔI _{Y(-)}	1		22		85	mApp		
Deflection Current Change with Ambient Temp.*	ΔI _Y /Ta	1	Ta = -20 ~ +70°C	-1.5		1.5	%		
Mid-point Voltage	V _{MID}	1		12.1	12.6	13.1	V		
Flyback Pulse Amplitude	V _(FBP)	1		47			V		
Flyback Pulse Width	τ _(FBP)	1		850	920	980	μs		
Static Circuit Current	I _{CQ}		V ₄₋₁ = 24V V ₉₋₁ = 24V V ₇₋₁ = 0			7	13	22	mA
Output Tr. Saturation Voltage	V ₄₋₂		V ₄₋₁ = V ₉₋₁ = 24V, Pin 2 - Pin 1 = 56Ω V ₆₋₁ = 0.3V, V ₇₋₁ = 0		2.7	3.7	V		
Output Tr. Saturation Voltage	V ₂₋₁		V ₄₋₁ = V ₉₋₁ = 24V, Pin 2 - Pin 4 = 56Ω V ₆₋₁ = 1.3V, V ₇₋₁ = 0		0.6	1	V		
Q21 Saturation Voltage	V ₈₋₁		V ₉₋₁ = 24V, Pin 9 - Pin 8 = 1.2kΩ V ₇₋₁ = 0V			0.5	V		
Thermal Resistance	R _{th(j-c)}					12	°C/W		

* Design reference value

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